

XP152A12C0MR-G

Power MOSFET

■ GENERAL DESCRIPTION

The XP152A12C0MR-G is a P-channel Power MOSFET with low on-state resistance and ultra high-speed switching characteristics.

Because high-speed switching is possible, the IC can be efficiently set thereby saving energy.

In order to counter static, a gate protect diode is built-in.

The small SOT-23 package makes high density mounting possible.

■ APPLICATIONS

- Notebook PCs
- Cellular and portable phones
- On-board power supplies
- Li-ion battery systems

■ FEATURES

Low On-State Resistance : $R_{ds(on)} = 0.3\Omega @ V_{gs} = -4.5V$
 : $R_{ds(on)} = 0.5\Omega @ V_{gs} = -2.5V$

Ultra High-Speed Switching

Gate Protect Diode Built-in

Driving Voltage : -2.5V

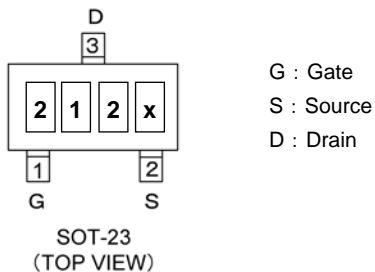
P-Channel Power MOSFET

DMOS Structure

Small Package : SOT-23

Environmentally Friendly : EU RoHS Compliant, Pb Free

■ PIN CONFIGURATION/MARKING



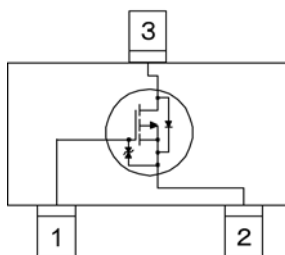
* x represents production lot number.

■ PIN ASSIGNMENT

PRODUCTS	PACKAGE	ORDER UNIT
XP152A12C0MR	SOT-23	3,000/Reel
XP152A12C0MR-G ^(*)	SOT-23	3,000/Reel

^(*) The "-G" suffix denotes Halogen and Antimony free as well as being fully RoHS compliant.

■ EQUIVALENT CIRCUIT



P-channel MOSFET
(1 device built-in)

■ ABSOLUTE MAXIMUM RATINGS

Ta = 25°C

PARAMETER	SYMBOL	RATINGS	UNITS
Drain - Source Voltage	Vdss	-20	V
Gate - Source Voltage	Vgss	±12	V
Drain Current (DC)	Id	-0.7	A
Drain Current (Pulse)	Idp	-2.8	A
Reverse Drain Current	Idr	-0.7	A
Channel Power Dissipation *	Pd	0.5	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55~150	°C

* When implemented on a ceramic PCB

XP152A12C0MR-G

ELECTRICAL CHARACTERISTICS

DC Characteristics

 $T_a = 25^{\circ}\text{C}$

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain Cut-Off Current	I_{dss}	$V_{ds} = -20\text{V}, V_{gs} = 0\text{V}$	-	-	-10	μA
Gate-Source Leak Current	I_{gss}	$V_{gs} = \pm 12\text{V}, V_{ds} = 0\text{V}$	-	-	± 10	μA
Gate-Source Cut-Off Voltage	$V_{gs(off)}$	$I_d = -1\text{mA}, V_{ds} = -10\text{V}$	-0.5	-	-1.2	V
Drain-Source On-State Resistance *1	$R_{ds(on)}$	$I_d = -0.4\text{A}, V_{gs} = -4.5\text{V}$	-	0.23	0.30	Ω
		$I_d = -0.4\text{A}, V_{gs} = -2.5\text{V}$	-	0.37	0.50	Ω
Forward Transfer Admittance *1	$ Y_{fs} $	$I_d = -0.4\text{A}, V_{ds} = -10\text{V}$	-	1.5	-	S
Body Drain Diode Forward Voltage	V_f	$I_f = -0.7\text{A}, V_{gs} = 0\text{V}$	-	-0.8	-1.1	V

*1 Effective during pulse test.

Dynamic Characteristics

 $T_a = 25^{\circ}\text{C}$

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Input Capacitance	C_{iss}	$V_{ds} = -10\text{V}, V_{gs} = 0\text{V}$ $f = 1\text{MHz}$	-	180	-	pF
Output Capacitance	C_{oss}		-	120	-	pF
Feedback Capacitance	C_{rss}		-	60	-	pF

Switching Characteristics

 $T_a = 25^{\circ}\text{C}$

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-On Delay Time	$t_d(on)$	$V_{gs} = -5\text{V}, I_d = -0.4\text{A}$ $V_{dd} = -10\text{V}$	-	5	-	ns
Rise Time	t_r		-	20	-	ns
Turn-Off Delay Time	$t_d(off)$		-	55	-	ns
Fall Time	t_f		-	70	-	ns

Thermal Characteristics

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal Resistance (Channel-Ambience)	$R_{th(ch-a)}$	Implement on a ceramic PCB	-	250	-	$^{\circ}\text{C/W}$